Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 2 X 0.75 (1.74 X 0.45 EP)
Lead Count	8
Terminal Finish	100 Sn
MS Number	MS010587B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.34E-03	86.9	869100	25.61	256128
Thermosets	Epoxy & Phenol Resin	Proprietary	4.91E-04	12.8	127800	3.77	37663
Other inorganic materials	Carbon black	1333-86-4	1.19E-05	0.3	3100	0.09	914
Subtotal			3.84 E-03	100.00	1000000	29.47	294705

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	8.08 E-03	97.5	975000	62.03	620318
Copper & its alloys	Iron	7439-89-6	1.95 E-04	2.35	23500	1.50	14951
Copper & its alloys	Zinc	7440-66-6	9.95 E-06	0.12	1200	0.08	763
Copper & its alloys	Phosphorus	7723-14-0	2.49 E-06	0.03	300	0.02	191
Subtotal			8.29 E-03	100.00	1000000	63.62	636224

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.40 E-04	100.0	1000000	1.84	18419

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.50 E-04	100.0	1000000	1.92	19186

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.96 E-05	99.0	990000	0.30	3039
Precious metals	Palladium	7440-05-3	4.00 E-07	1.0	10000	0.00	31
Subtotal			4.00 E-05	1000000	99.00	0.31	3070

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.10 E-04	100.0	1000000	1.61	16117

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.24 E-04	77.71	777100	0.95	9542
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	4.98 E-06	3.11	31100	0.04	382
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	4.98 E-06	3.11	31100	0.04	382
Other organic materials	Butyrolactone, gamma-	96-48-0	4.98 E-06	3.11	31100	0.04	382
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	4.98 E-06	3.11	31100	0.04	382
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	4.98 E-06	3.11	31100	0.04	382
Other organic materials	Organosilane	TS ref# 10001	4.98 E-06	3.11	31100	0.04	382
Other inorganic materials	Copper(II) oxide	1317-38-0	4.98 E-06	3.11	31100	0.04	382
Other organic materials	Epoxy resin modifier	TS ref# 10038	8.32 E-07	0.52	5200	0.01	64
Subtotal			1.60 E-04	100.0	1000000	1.23	12279

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.30 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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